



US00D868013S

(12) **United States Design Patent**
Karasawa

(10) **Patent No.:** **US D868,013 S**

(45) **Date of Patent:** **** Nov. 26, 2019**

(54) **CASSETTE RECEIVING TOOL FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

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(**) Term: **15 Years**

(21) Appl. No.: **29/610,856**

(22) Filed: **Jul. 17, 2017**

(30) **Foreign Application Priority Data**

Jan. 18, 2017 (JP) 2017-000730

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182, 184, 199; D15/144, 144.1, D15/199, 140; 294/1.1, 2, 6, 12, 15, 16, 294/26-34, 49, 55.5, 87.1; 16/114 R; 118/500, 503, 728; 206/328, 334, 445, 206/454; 414/416, 217, 940, 331, 935, 414/939; 451/364; 269/903; 248/694
CPC B65G 49/07; H01L 21/673; H01L 21/67; H01L 21/67353; H01L 21/67769; H01L 21/67775; H01L 21/67379; H01L 23/32; B65D 25/28

See application file for complete search history.

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(57) **CLAIM**

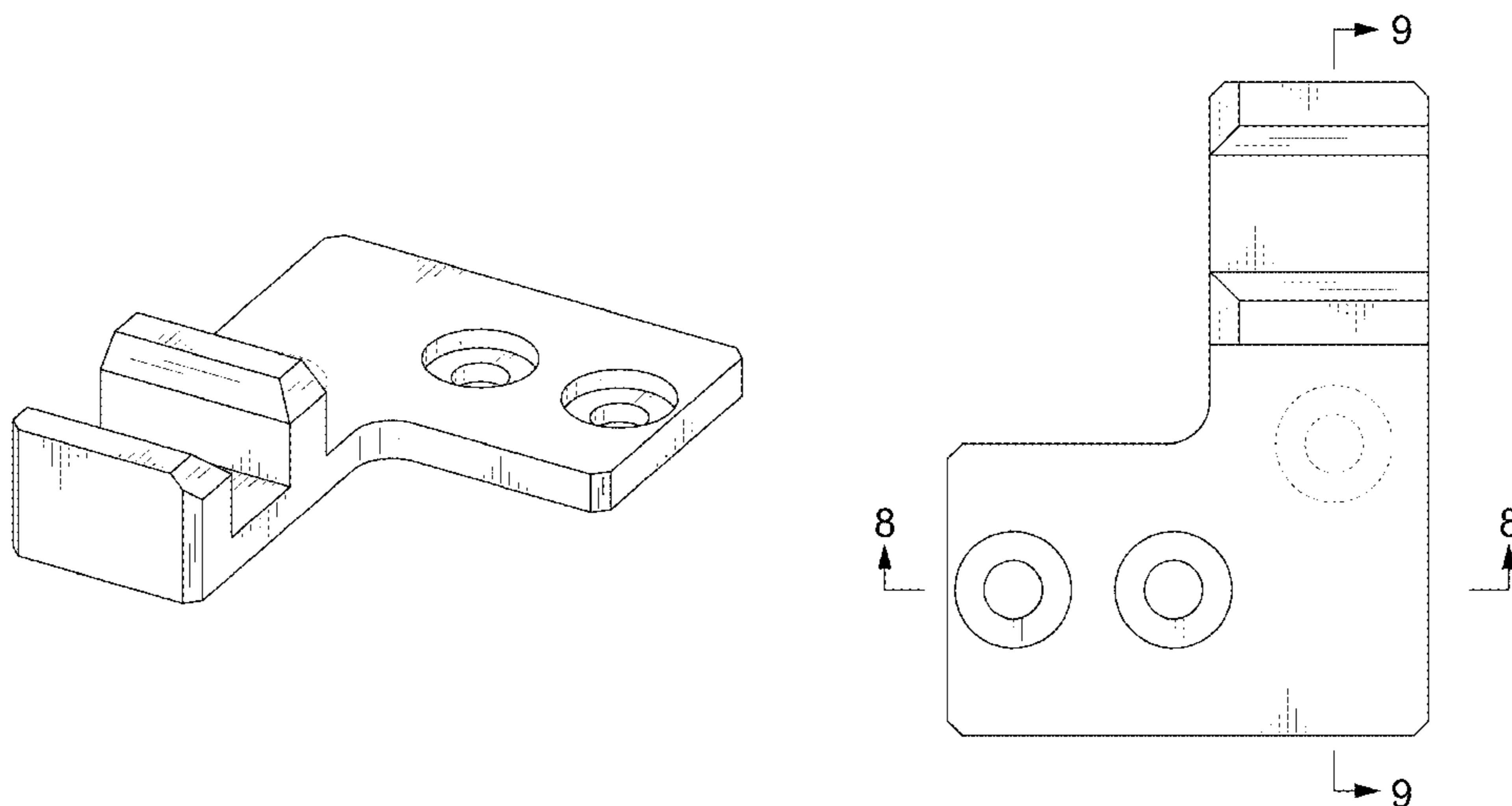
The ornamental design for a cassette receiving tool for semiconductor manufacturing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front, top, and left side perspective view of a cassette receiving tool for semiconductor manufacturing apparatus, showing my new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof;
FIG. 8 is a cross sectional view taken along line 8-8 in FIG. 2; and,
FIG. 9 is a cross sectional view taken along line 9-9 in FIG. 2.

The broken lines shown in the drawings represent portions of the cassette receiving tool for semiconductor manufacturing apparatus that form no part of the claimed design.

1 Claim, 3 Drawing Sheets



(56)

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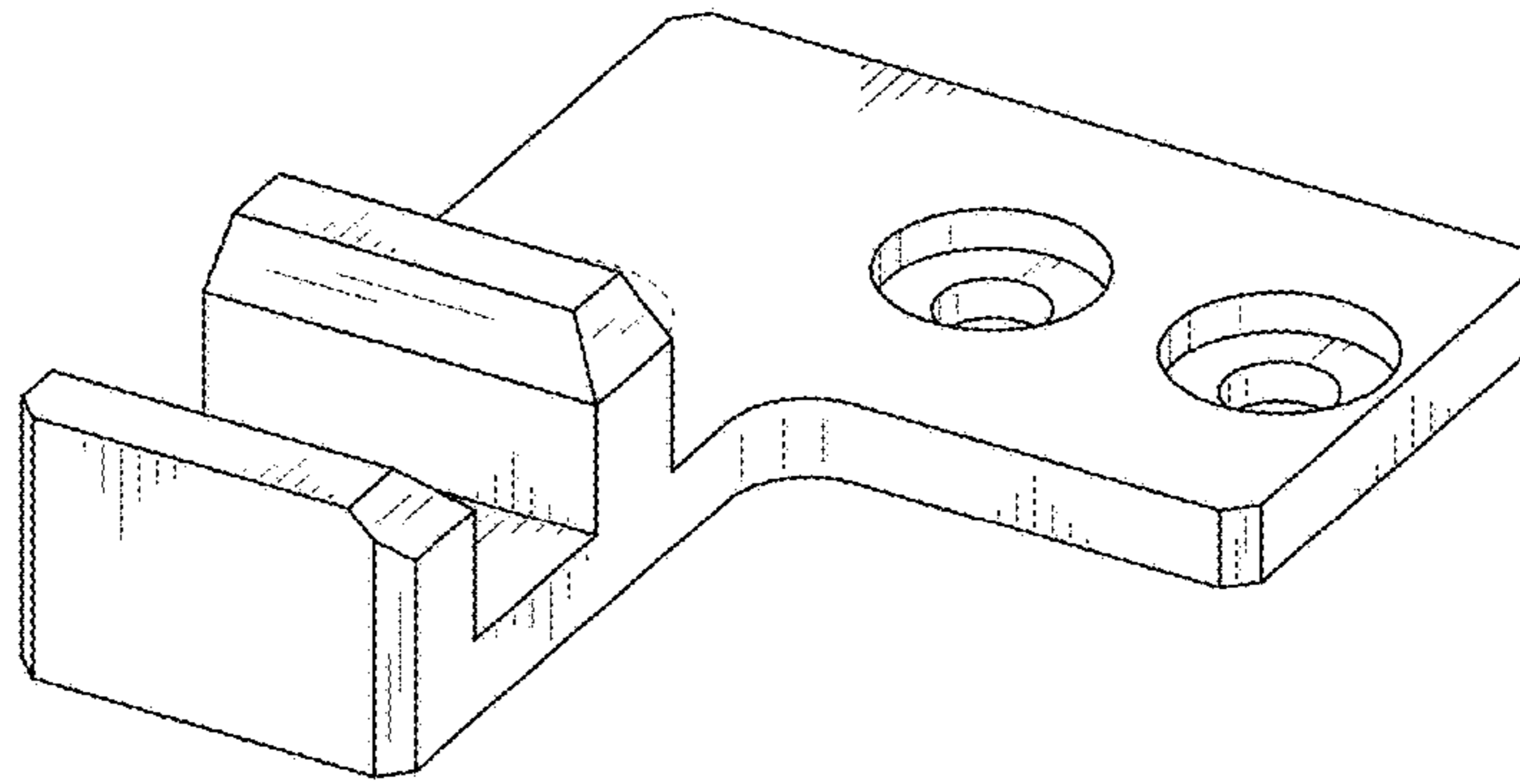


FIG. 1

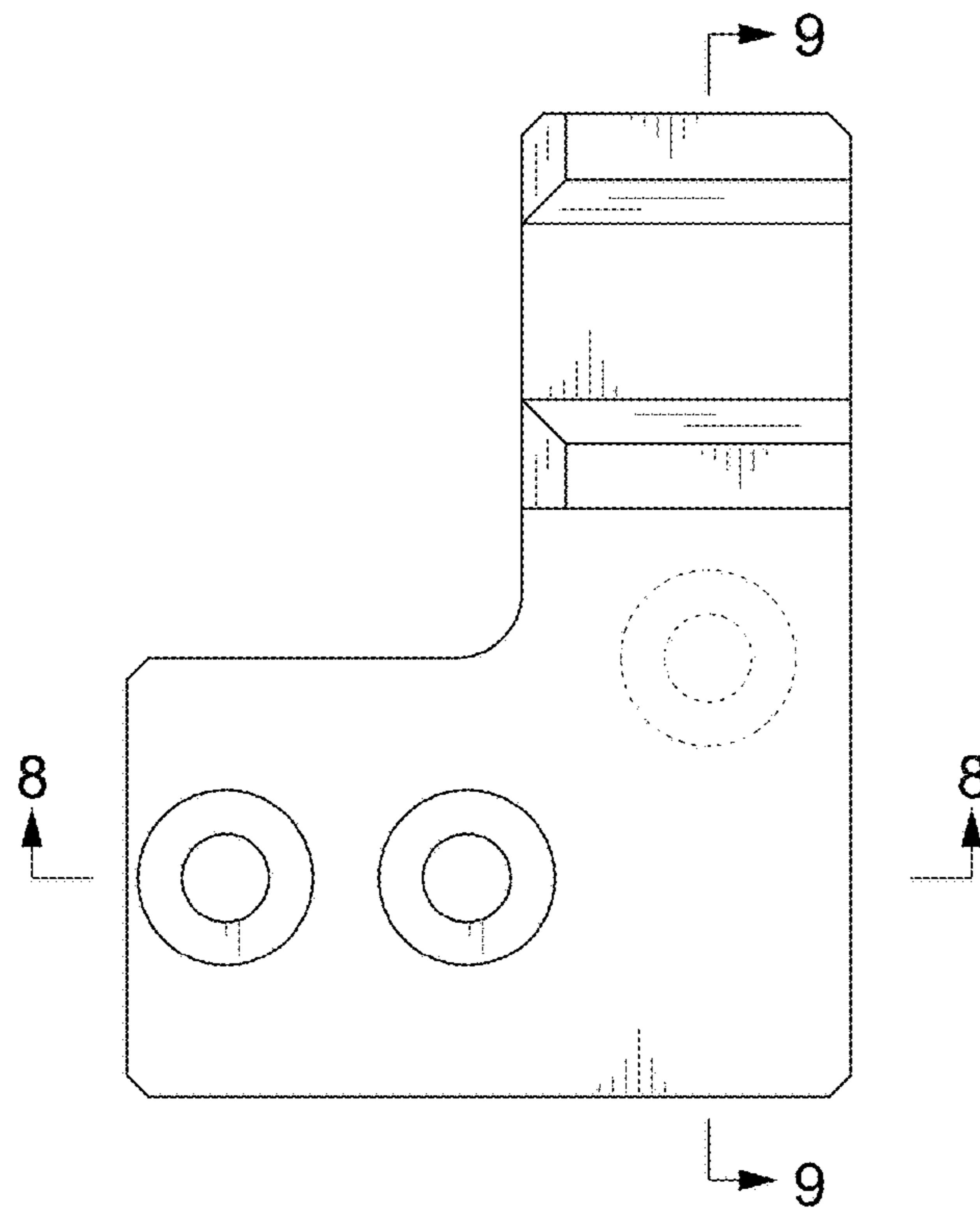


FIG. 2

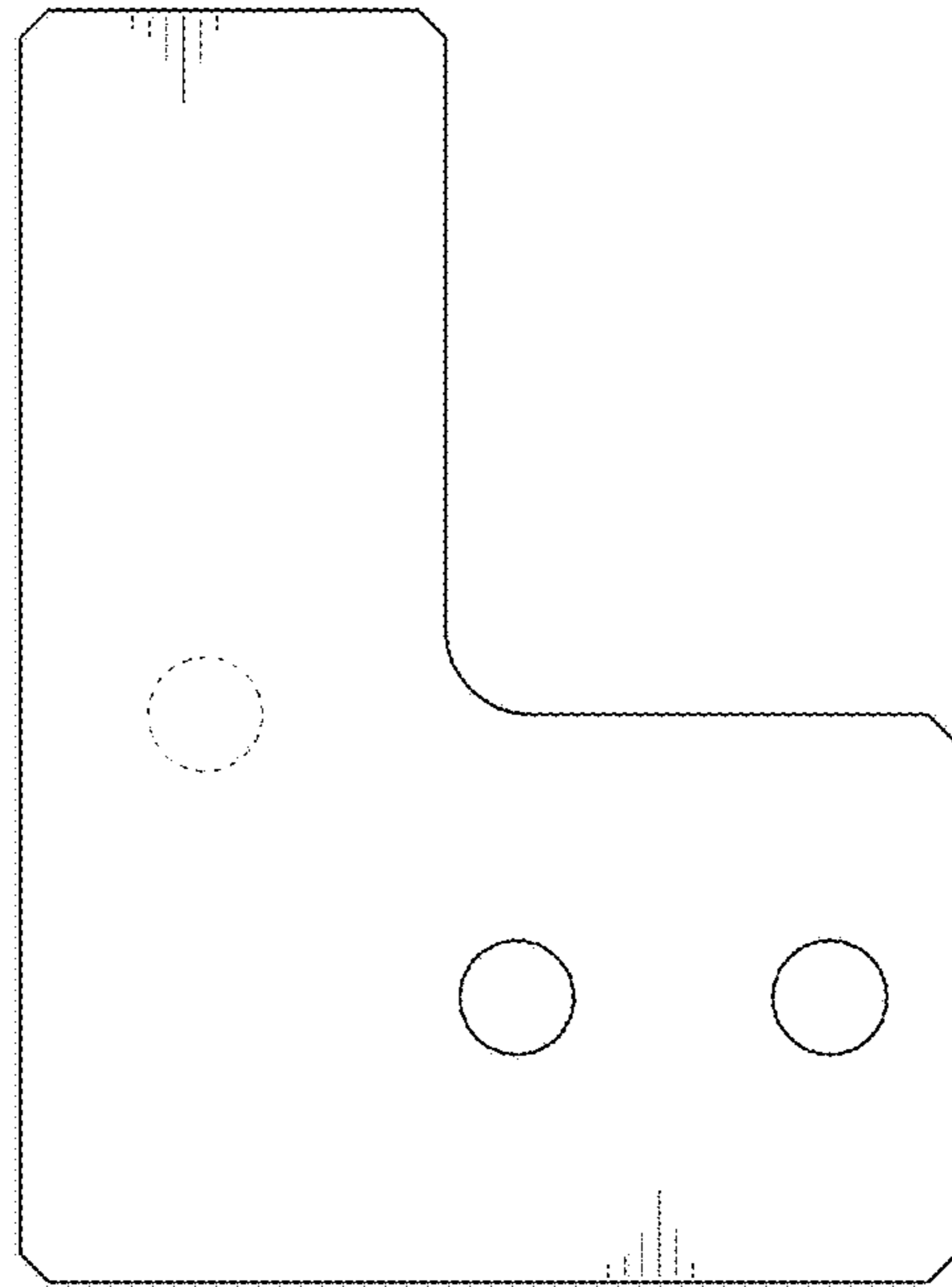


FIG. 3

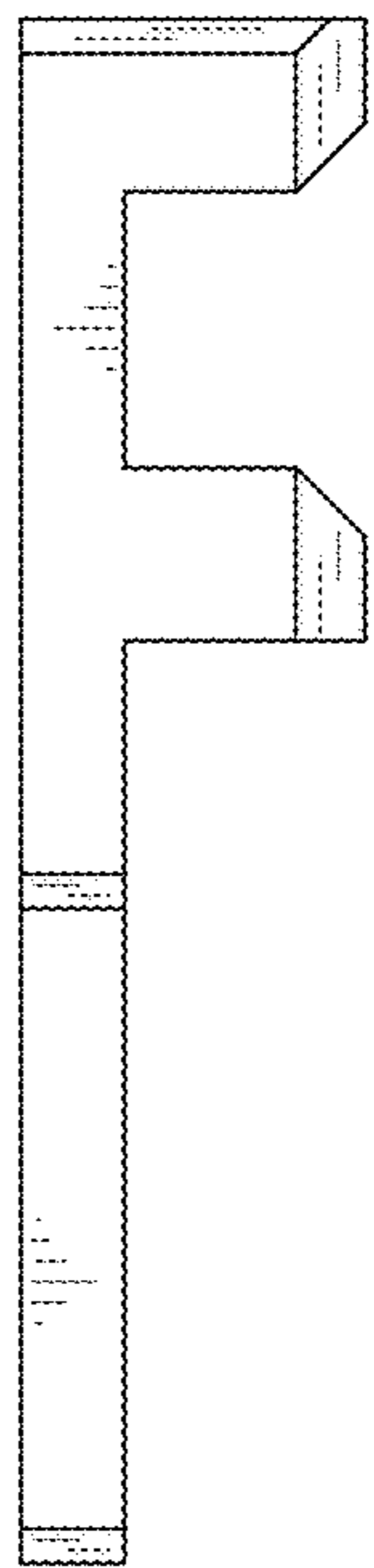


FIG. 4

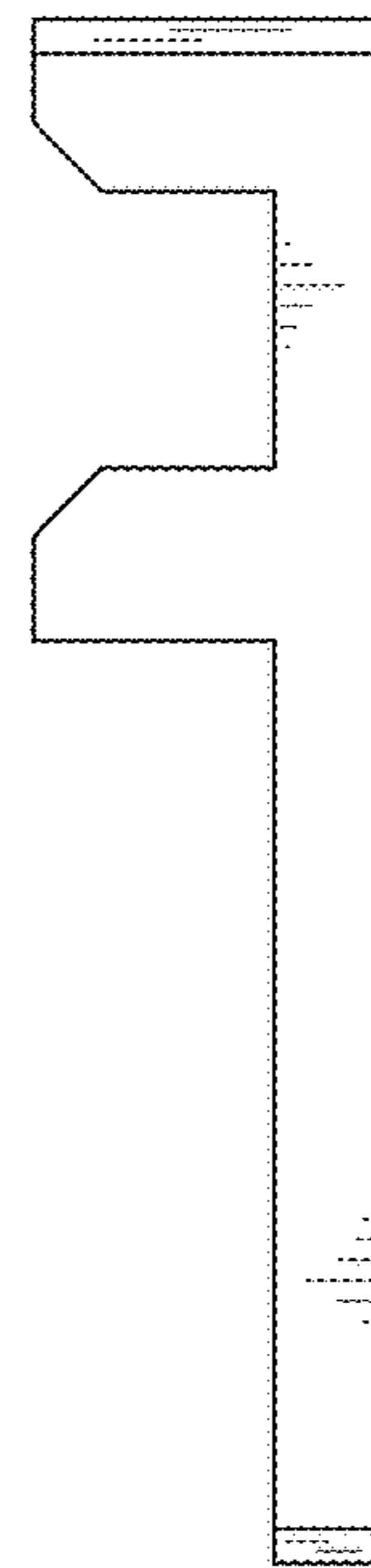


FIG. 5

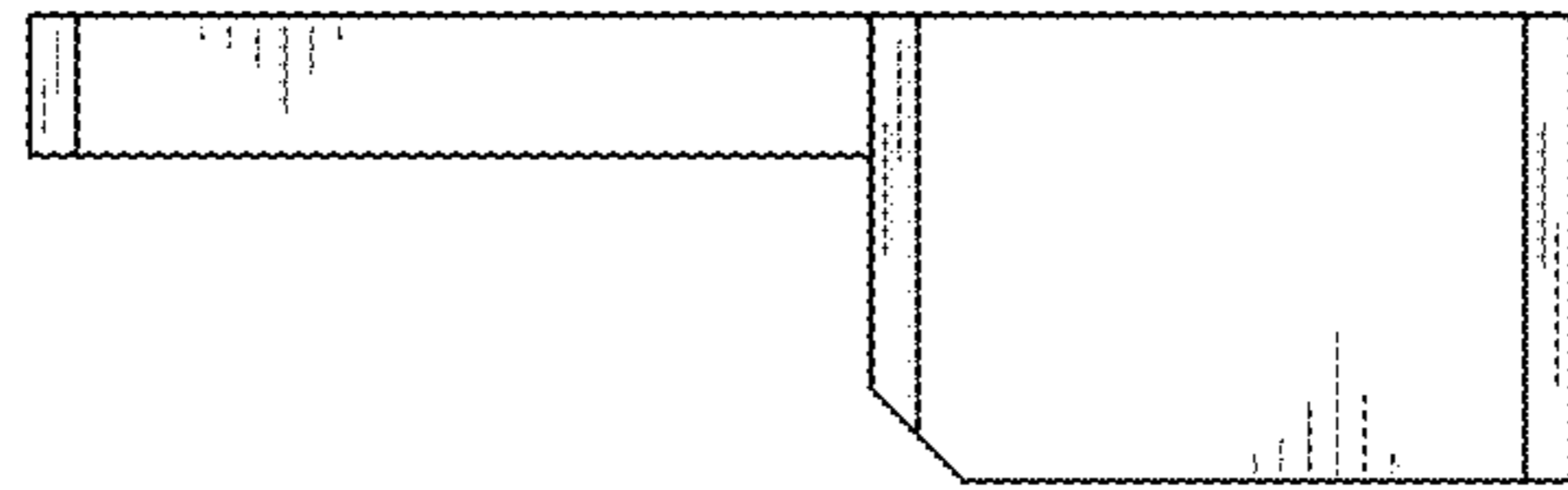


FIG. 6

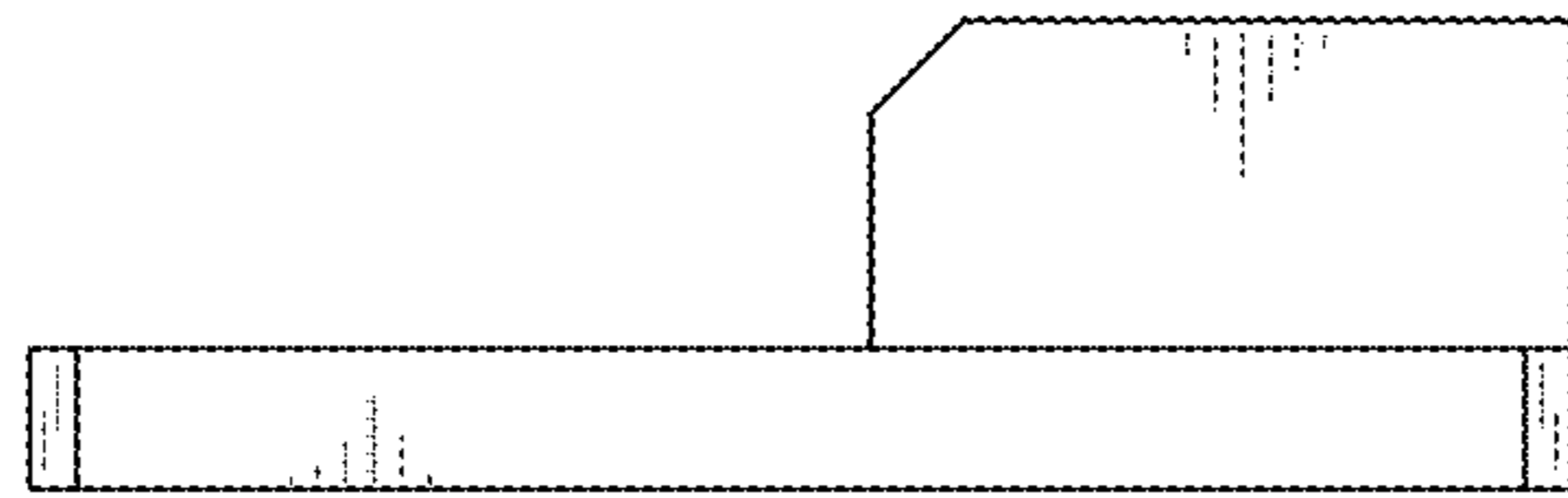


FIG. 7

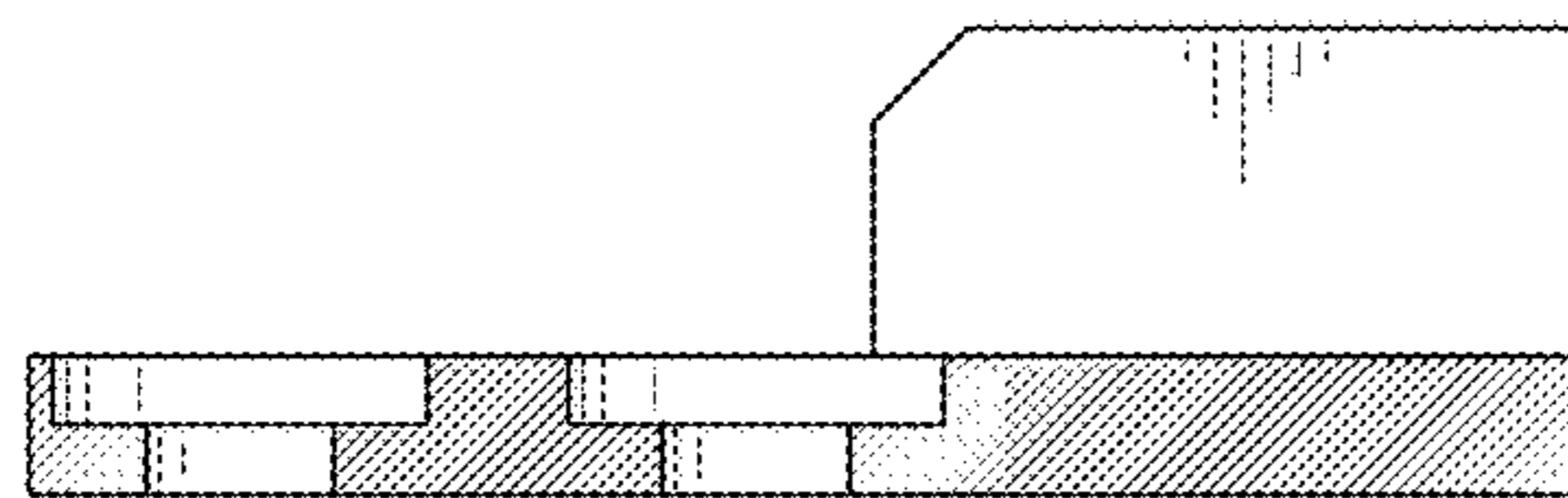


FIG. 8

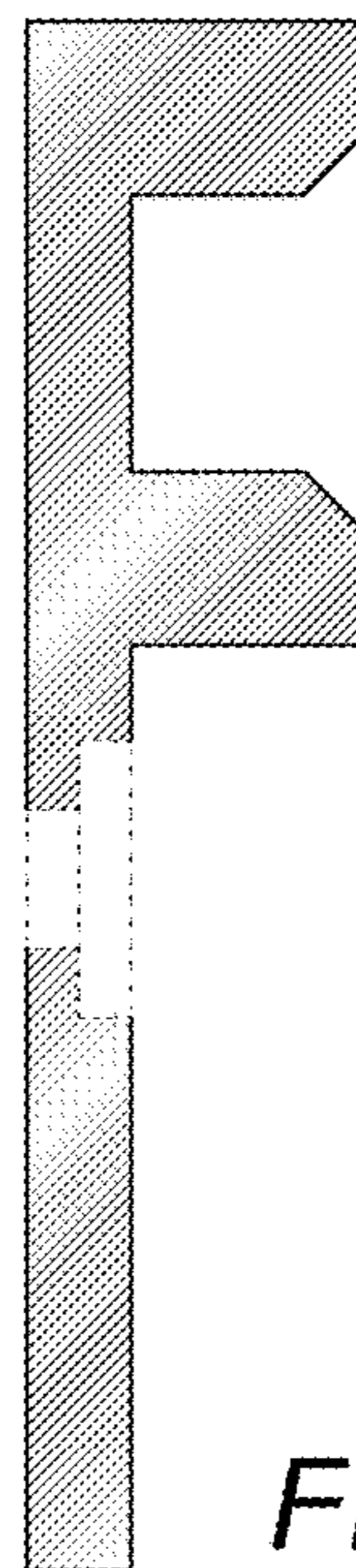


FIG. 9